

## IN THE SPECIFICATION

Please replace the paragraph at page 25, lines 16-27 as amended in the Preliminary Amendment filed July 21, 2006, as follows:

Further, wafer W3 taken out from the same carrier C to be subjected to the third processing is delivered by second transfer means 23 via delivery stage 24 of carrier block B1 to third transfer means 82 via delivery unit TRS1 of third process block S3 for example, and in process block S3, it is transferred in the order of, e.g., temperature regulating unit (CPL) → lower-layer anti-reflection coating forming unit (BARC) → vacuum drying unit (VD) → heating unit (LHP), to form the lower-layer anti-reflection coating, and then transferred in the order of temperature regulating unit (CPL) → coating unit (COT) → vacuum drying unit (VD) → heating unit (PAB), to be subjected to the resist solution coating processing. Thereafter, it is transferred along the path of delivery unit TRS2 for output → second transfer means 23 of transfer block B2 → delivery stage 27 of interface portion B5 → delivery means 26 → light exposure device B6, where prescribed light exposure processing is carried out.